

PATENT ABSTRACTS OF JAPAN

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(71)Applicant : MICRONICS JAPAN CO LTD

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(54) HEAD FOR INSPECTING FLAT PLATE-LIKE BODY

(57)Abstract:

PROBLEM TO BE SOLVED: To surely act a required needle pressure and facilitate production by projecting and arranging one end of a contact pin from a holder and arranging a connection pin connecting the contact pin with a land part of a substrate at an elastic plate.

SOLUTION: When an inspection head is pressed to an integrated circuit chip (body to be inspected) 12 at the time of a conduction inspection, a contact pin 22 is slightly pressed back to an elastic plate 24 which can be elastically deformed in three directions orthogonal to one another, projecting an upper end part slightly from a holder 20 and pressing a connecting pin 26 toward a land part 44 of a wiring board 28. As a result, the elastic plate 24 is elastically deformed. At this time, the contact pin 22 is maintained in a state to be in contact with an electrode 14 of the chip 12 without being deformed, with acting a predetermined needle pressure to the electrode 14 because of the deformation of the elastic plate 24. Since the connecting pin 26 is arranged at the elastically deformable elastic plate 24, the inspection head can be manufactured easily with an L-shaped curved probe eliminated.

